



## 1-Line Low Capacitance Bi-directional TVS Diode

### General description

GBLC03C a 3.3V bi-directional TVS diode, utilizing leading monolithic silicon technology to provide fast response time and low ESD clamping voltage, making his device an ideal solution for protecting voltage sensitive high-speed data lines. The GBLC03C has a low capacitance with a typical value at 1.0pF, and complies with the IEC61000-4-2(ESD) standard with  $\pm 30\text{KV}$  air and  $\pm 30\text{KV}$  contact discharge. It is assembled into a leadfree SOD-323 package. The small size, low capacitance and high ESD surge protection make GBLC03C an idea choice to protect cell phone, wireless systems, and communication equipment.

### Features and benefits

- Ultra Low Capacitance 0.6 pF(Typ)
- 360W peak pulse power (8/20 $\mu\text{s}$ )
- Working Voltage 3.3V
- Low leakage current: nA Level
- Complies with following standards:
  - IEC 61000-4-2 (ESD) immunity test
    - Air discharge:  $\pm 30\text{KV}$
    - Contact discharge:  $\pm 30\text{KV}$
  - IEC61000-4-5 (Lightning) 20A (8/20 $\mu\text{s}$ )
  - IEC61000-4-4 (EFT) 80A (5/50nS)
- RoHS compliant

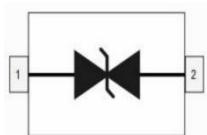
### Application information

- High- speed data lines
- Smart phones
- USB Ports
- Wireless Systems
- Ethernet 10/100/1000 Base T

### Ordering information

Part Number	Package	Packaging	Reel Size
GBLC03C	SOD323	3000/Tape & Reel	7 inch

### Schematic & Pin configuration

Simplified outline	Graphic symbol
	

**Maximum Ratings** ( $T_A = 25^\circ C$ , unless otherwise specified)

Parameter	Symbol	Value	Unit
Peak Pulse Power ( $tp = 8/20\mu s$ )	$P_{pk}$	360	W
Peak Pulse Current( $tp = 8/20\mu s$ )	$I_{pp}$	20	A
ESD voltage IEC 61000-4-2 (air discharge)	$V_{ESD}$	30	kV
ESD voltage IEC 61000-4-2 (contact discharge)	$V_{ESD}$	30	kV
Storage Temperature Range	$T_{stg}$	-55 to +150	°C
Operating Temperature Range	$T_{op}$	-40 to +85	°C

**Electrical Characteristics** ( $T_A = 25^\circ C$ , unless otherwise specified)

Parameter	Symbol	Min	Typ	Max	Unit	Condition
Reverse Working Voltage	$V_{RWM}$	--	--	3.3	V	
Breakdown Voltage	$V_{BR}$	4.0	5.0	6.0	V	$I_t=1mA$
Leakage Current $I_{leak}$	$I_R$	--	--	0.1	μA	$V_{RWM}=3.3V$
Clamping Voltage	$V_C$	--	8.0	--	V	$I_{pp}=5A, tp=8/20\mu s$
Clamping Voltage	$V_C$	--	17.0	18.0	V	$I_{pp}=20A, tp=8/20\mu s$
Junction Capacitance	$C_J$	--	0.6	1.0	pF	$V_R=0V, f=1MHz$

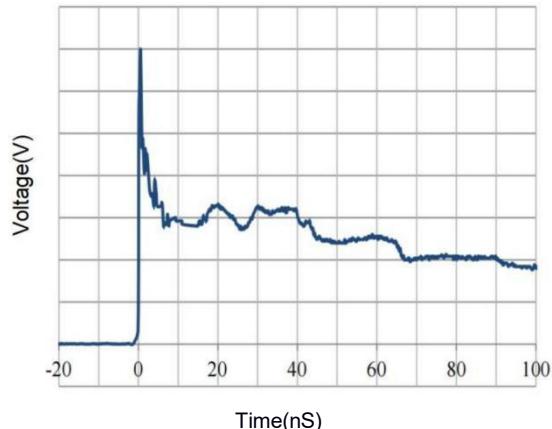
**Portion Electronics Parameter**

Symbol	Parameter
$I_{pp}$	Reverse Peak Pulse Current
$V_C$	Clamping Voltage @ IPP
$V_{RWM}$	Working Peak Reverse Voltage
$I_R$	Reverse Leakage Current @ VRWM
$V_{BR}$	Breakdown Voltage @ IT
$I_T$	VBR Test Current

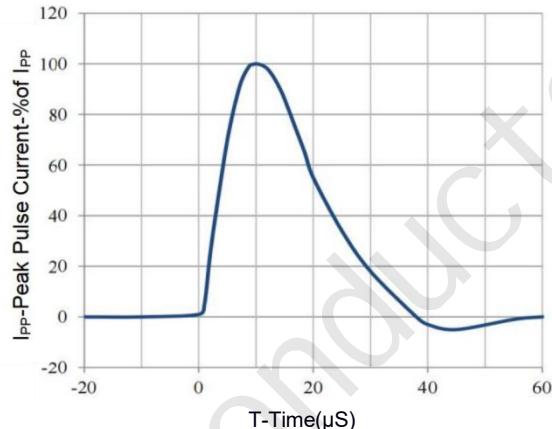
The graph plots current (I) on the vertical axis against voltage (V) on the horizontal axis. Key points marked on the curve are:
 

- $V_C$ : Clamping Voltage at  $I_{pp}$ .
- $V_{BR}$ : Breakdown Voltage at  $I_T$ .
- $V_{RWM}$ : Working Peak Reverse Voltage at  $I_R$ .
- $I_{pp}$ : Reverse Peak Pulse Current.
- $I_T$ : VBR Test Current.
- $I_R$ : Reverse Leakage Current at  $V_{RWM}$ .
- $I_L$ : Reverse Leakage Current at  $V_C$ .
- $V_B$ : Breakdown Voltage at  $I_{pp}$ .
- $I_{pp}$ : Reverse Peak Pulse Current at  $V_B$ .

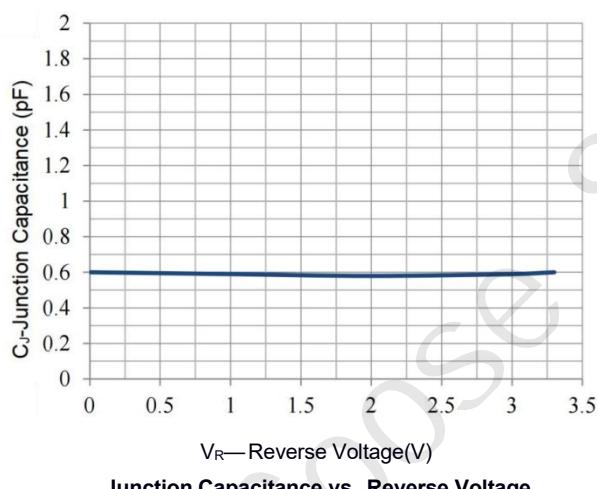
### Typical Performance Characteristics ( $T_A=25^\circ\text{C}$ unless otherwise Specified)



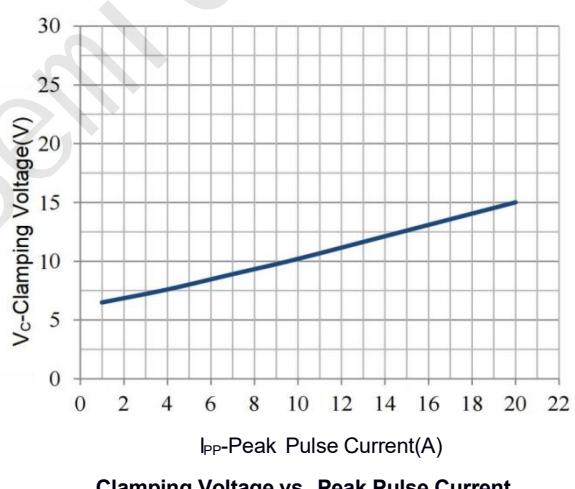
**IEC61000-4-2 Pulse Waveform**



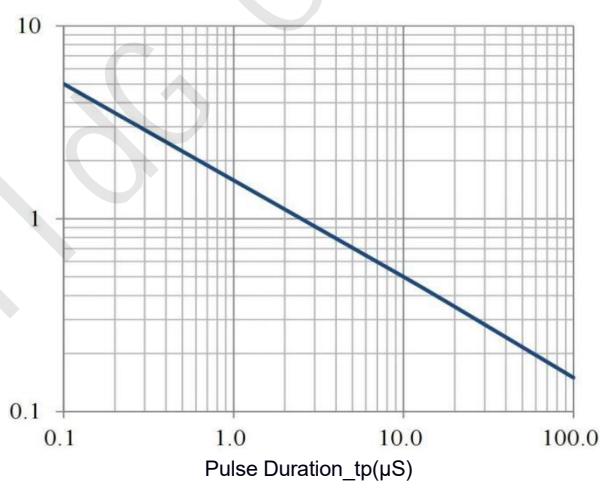
**IEC61000-4-5 8X20μs Pulse Waveform**



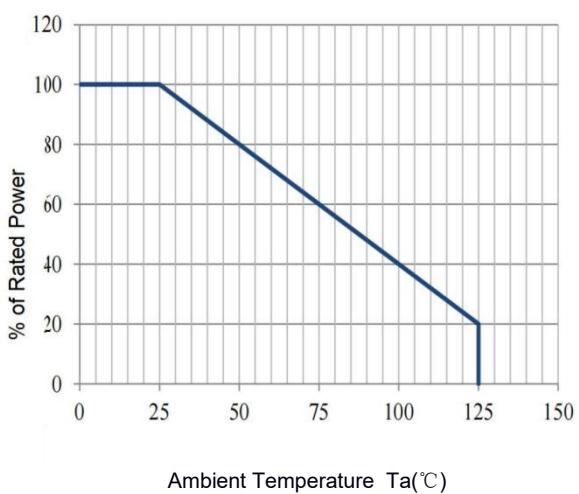
**Junction Capacitance vs. Reverse Voltage**



**Clamping Voltage vs. Peak Pulse Current**



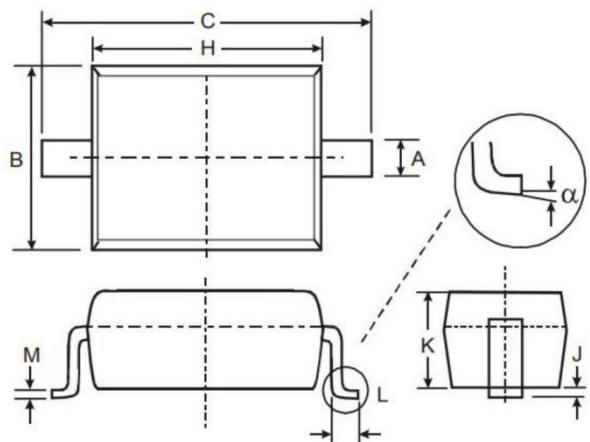
**Peak Pulse Power vs. Pulse Time**



**Power Derating Curve**

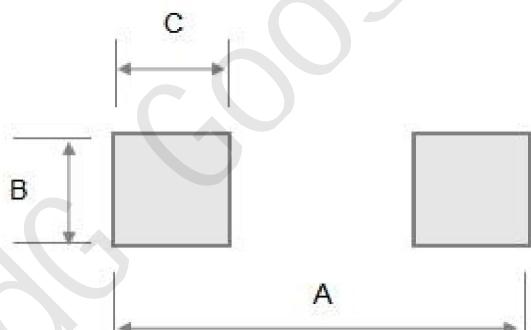
### Package Outline Dimensions (mm)

**SOD323**



SYMBOL	DIMENSIONS	
	MIN	MAX
A	0.25	0.40
B	1.20	1.40
C	2.35	2.75
H	1.50	1.80
J	0.01	0.15
K	0.75	1.05
L	0.20	0.40
M	0.08	0.25
“	0°	8°

### Soldering Footprint (mm)



SYMBOL	DIMENSIONS
A	3.20
B	0.80
C	0.80